

**OFFICIAL**

19 PAGES TOTAL

BY TELEFAX TO:  
(703) 872-9310  
=====

DOCKET NO.: 4029

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

## IN THE MATTER OF THE APPLICATION FOR PATENT

OF: Michio OSADA et al. | Art Unit: 1722

SERIAL NO.: 09/705,237 | Confirmation No.: 4586

FILED: November 2, 2000 | EX.: Thukhanh T. Nguyen

FOR: Die Used for Resin-Sealing and  
Molding an Electronic ComponentASSISTANT COMMISSIONER FOR PATENTS  
BOX RESPONSE - NO FEE  
WASHINGTON, D.C. 20231

January 31, 2003

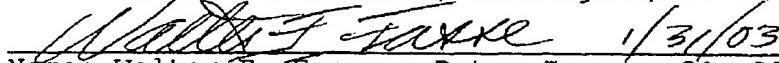
TRANSMITTED HEREWITH IS A RESPONSE TO THE OFFICE ACTION OF OCTOBER 31, 2002 IN THE ABOVE IDENTIFIED PATENT APPLICATION COMPRISING 14 PAGES. A MARKED-UP VERSION OF AMENDED SPECIFICATION PAGES 4, 6 AND 7 IS ENCLOSED. A MARKED-UP VERSION OF AMENDED CLAIMS 1, 5 AND 7 IS ENCLOSED.

NO ADDITIONAL CLAIM FEE IS REQUIRED, AS SHOWN BELOW.

CLAIMS RE- MAINING AFTER AMENDMENT	HIGHEST NO. PREVIOUSLY PAID FOR	PRESENT EXTRA	SMALL ENTITY	OR	LARGE ENTITY	ADDITIONAL FEE
TOTAL: 11	MINUS: 20	0	X=\$		X=\$0	=\$0
INDEP: 2	MINUS: 3	0	X=\$		X=\$0	=\$0
					TOTAL ADDITION. FEE DUE:	=\$0

CERTIFICATE OF FAX TRANSMISSION:

I hereby certify that this correspondence with all indicated enclosures is being transmitted by telefax to (703) 872-9310 on the date indicated below, and is addressed to: Assistant Commissioner for Patents, Washington, D. C. 20231.

  
 Name: Walter F. Fasse - Date: January 31, 2003

4029/WFF:ar

Received from &lt;207 862 4681&gt; at 1/31/03 5:17:06 PM [Eastern Standard Time]

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